# PRELIMINARY DATA SHEET



Solid State Relay OCMOS FET

# **PS7802B-1A**

# 4-PIN ULTRA SMALL FLAT-LEAD, LOW C $\times$ R (6.3 pF • $\Omega$ )

1-ch Optical Coupled MOS FET

-NEPOC Series-

#### DESCRIPTION

**KENESAS** 

The PS7802B-1A is a low output capacitance solid state relay containing a GaAs LED on the light emitting side (input side) and MOS FETs on the output side.

An ultra small flat-lead package has been provided which realizes a reduction in mounting area of about 50% compared with the PS72xx series.

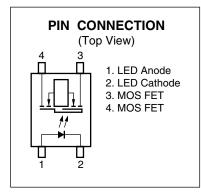
It is suitable for high-frequency signal control, due to its low C × R (6.3 pF  $\cdot \Omega$ ), low output capacitance, and low off-state leakage current.

#### FEATURES

- Ultra small flat-lead package (4.2 (L)  $\times$  2.5 (W)  $\times$  1.85 (H) mm)
- Low  $C \times R$  ( $C \times R = 6.3 \text{ pF} \cdot \Omega$ )
- 1 channel type (1 a output)
- Designed for AC/DC switching line changer
- Low offset voltage
- Ordering number of taping product: PS7802B-1A-F3: 3 500 pcs/reel

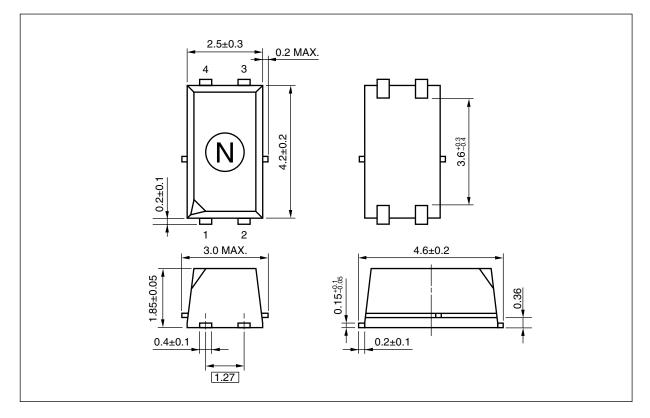
#### **APPLICATIONS**

• Measurement equipment

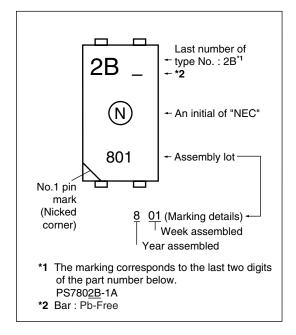


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# PACKAGE DIMENSIONS (UNIT: mm)



#### MARKING EXAMPLE



# **ORDERING INFORMATION**

Part Number	Order Number	Solder Plating Specification	Packing Style
PS7802B-1A	PS7802B-1A-A	Pb-Free	50 pcs (Tape 50 pcs cut)
PS7802B-1A-F3	PS7802B-1A-F3-A		Embossed Tape 3 500 pcs/reel

# ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	lf	50	mA
	Reverse Voltage	VR	5.0	V
	Power Dissipation	PD	50	mW
	Peak Forward Current <sup>*1</sup>	IFP	1	А
MOS FET	Break Down Voltage	VL	40	V
	Continuous Load Current	l.	240	mA
	Pulse Load Current <sup>*2</sup> (AC/DC Connection)	Ilp	360	mA
	Power Dissipation	PD	250	mW
Isolation Voltage <sup>3</sup>		BV	500	Vr.m.s.
Total Power Dissipation		Ρτ	300	mW
Operating Ambient Temperature		TA	–40 to +85	°C
Storage Temperature		Tstg	-40 to +100	°C

\***1** PW = 100 μs, Duty Cycle = 1%

\*2 PW = 100 ms, 1 shot

\*3 AC voltage for 1 minute at  $T_A = 25^{\circ}$ C, RH = 60% between input and output Pins 1-2 shorted together, 3-4 shorted together.

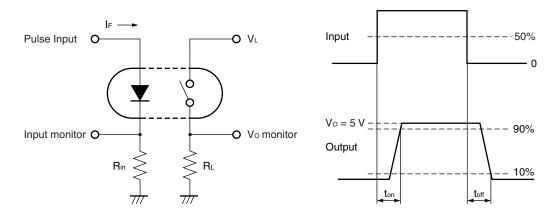
# **RECOMMENDED OPERATING CONDITIONS (TA = 25°C)**

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lf	4.5	5	20	mA
LED Off Current	lf	0.1			mA

# ELECTRICAL CHARACTERISTICS (TA = 25°C)

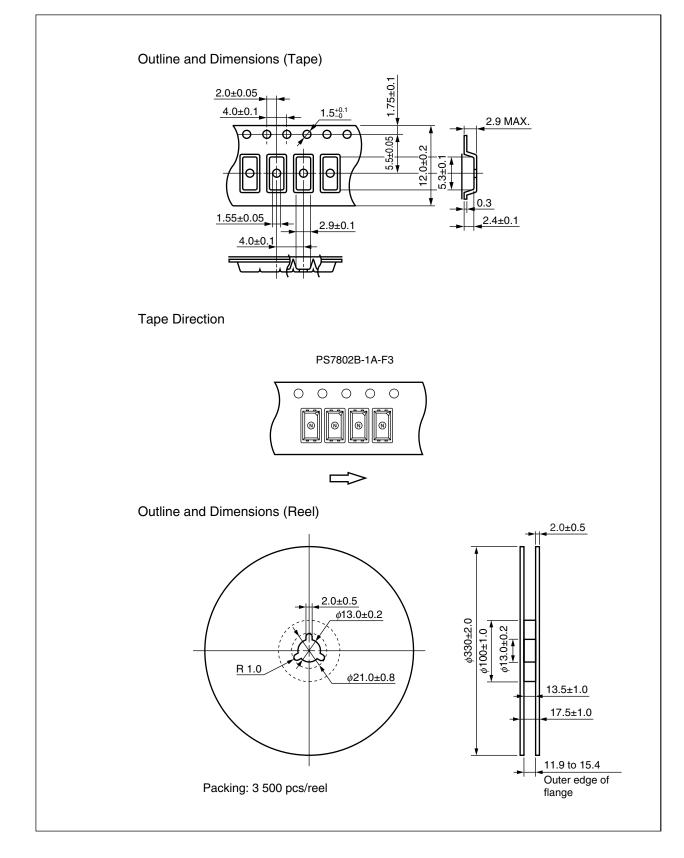
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 5 mA		1.1	1.4	V
	Reverse Current	IR	V <sub>R</sub> = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	Loff	V <sub>D</sub> = 40 V		0.1	1	nA
	Output Capacitance	Cout	$V_D = 0 V$ , f = 1 MHz, t $\leq$ 1 s		2.5	3.7	pF
Coupled	LED On-state Current	IFon	I∟ = 240 mA			4	mA
	On-state Resistance	Ron	$I_{\text{F}}$ = 5 mA, $I_{\text{L}}$ = 240 mA, $t \leq$ 10 ms		2.5	3.5	Ω
	Turn-on Time <sup>*1, 2</sup>	ton	I⊧ = 5 mA, V₀ = 5 V, R∟ = 500 Ω,		0.2	0.5	ms
	Turn-off Time <sup>*1, 2</sup>	toff	PW ≥ 1.0 ms		0.05	0.5	
	Isolation Resistance	RI-0	VI-O = 0.5 kVDC	10 <sup>°</sup>			Ω
	Isolation Capacitance	CI-0	V = 0 V, f = 1 MHz		0.3		pF

\*1 Test Circuit for Switching Time



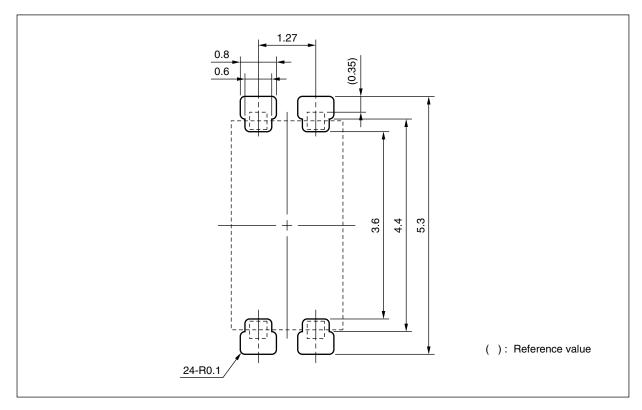
\*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 1.0 ms.
 Be aware that when the device operates with an input-pulse width less than 1.0 ms, the turn-on time and turn-off time will increase.

# TAPING SPECIFICATIONS (UNIT: mm)





# **RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)**



**Remark** All dimensions in this figure must be evaluated before use.



#### **RECOMMENDED SOLDERING CONDITIONS**

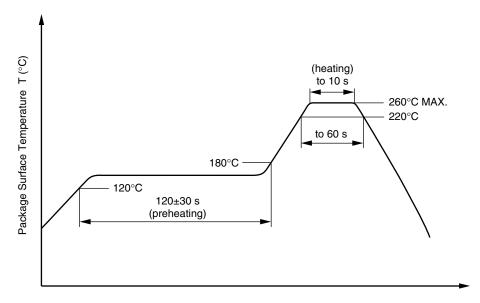
# (1) Infrared reflow soldering

- Peak reflow temperature
- Time of peak reflow temperature
- Time of temperature higher than 220°C
- Time to preheat temperature from 120 to 180°C
- Number of reflows
- Flux

260°C or below (package surface temperature) 10 seconds or less 60 seconds or less 120±30 s Three

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### Recommended Temperature Profile of Infrared Reflow



Time (s)

#### (2) Wave soldering

<ul> <li>Temperature</li> </ul>	260°C or below (molten solder temperature)
• Time	10 seconds or less

- Time TO seconds of
- Preheating conditions 120°C or below (package surface temperature)
- Number of times
   One
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### (3) Soldering by soldering iron

<ul> <li>Peak temperature (lead part temperature)</li> </ul>	350°C or below
Time (each pins)	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a
	maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

#### (4) Cautions

• Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.



## USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.
	• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	<ol> <li>Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li> </ol>
	<ol><li>Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li></ol>
	• Do not burn, destroy, cut, crush, or chemically dissolve the product.
	<ul> <li>Do not lick the product or in any way allow it to enter the mouth.</li> </ul>